

## Overview

The KEMET T428 Series was developed to provide the volumetric efficiency of a conformally coated capacitor in a pick-and-place friendly molded package. The planarity of the molded package eliminates the “drops” associated with the conformally coated tantalum surface mount devices. This new package

design offers the highest CV/cc of any molded leadframe product. In addition, the facedown construction offers higher power ratings per cc. The robust design features and testing protocol make this part suitable for application in the telecommunications, industrial, military and aerospace markets.

## Benefits

- High CV/cc
- Taped and reeled per EIA 481-1
- SnPb termination finish
- Laser-marked case
- 100% surge current test available
- Halogen-free epoxy
- Capacitance values of 15 to 470  $\mu$ F
- Tolerances of  $\pm 5\%$ ,  $\pm 10\%$  and  $\pm 20\%$
- Voltage rating of 4 to 50 VDC
- Extended range values
- Pick-and-place friendly
- RoHS Compliant and lead-free terminations available
- Operating temperature range of  $-55^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$

## Applications

Typical applications include decoupling and filtering in telecommunications, computer, industrial, defense and aerospace applications.



## Environmental Compliance

RoHS Compliant (6/6) according to Directive 2002/95/EC when ordered with 100% Sn solder.



RoHS Compliant

## SPICE

For a detailed analysis of specific part numbers, please visit [www.kemet.com](http://www.kemet.com) for a free download of KEMET's SPICE software. The KEMET SPICE program is freeware intended to aid design engineers in analyzing the performance of these capacitors over frequency, temperature, ripple, and DC bias conditions.

## Ordering Information

T	428	P	227	K	006	A	H	61	10
Capacitor Class	Series	Case Size	Capacitance Code (pF)	Capacitance Tolerance	Voltage	Failure Rate/ Design	Lead Material	Surge	ESR
T = Tantalum	High Volumetric Efficient Facedown Hi-Rel MnO <sub>2</sub> COTS	P	First two digits represent significant figures. Third digit specifies number of zeros.	J = ±5% K = ±10% M = ±20%	004 = 4 V 006 = 6.3 V 010 = 10 V 015 = 15 V 020 = 20 V 025 = 25 V 035 = 35 V 050 = 50 V	A = N/A B = 0.1%/1,000 hours	H = Standard solder coated (SnPb 5% Pb) T = 100% tin (Sn)	61 = None 62 = 10 cycles, 25°C 63 = 10 cycles, -55°C and 85°C	10 = Standard 20 = Low 30 = Ultra-low

## Performance Characteristics

Item	Performance Characteristics
Operating Temperature	-55°C to 125°C
Rated Capacitance Range	15 – 470 µF @ 120 Hz/25°C
Capacitance Tolerance	J Tolerance (5%), K Tolerance (10%), M Tolerance (20%)
Rated Voltage Range	4 – 50 V
DF (120 Hz)	Refer to Part Number Electrical Specification Table
ESR (100 kHz)	Refer to Part Number Electrical Specification Table
Leakage Current	≤ 0.01 CV (µA) at rated voltage after 5 minutes

## Qualification

Test	Condition	Characteristics				
Endurance	85°C @ rated voltage, 2,000 hours 125°C @ 2/3 rated voltage, 2,000 hours	Δ C/C	Within ±10% of initial value			
		DF	Within initial limits			
		DCL	Within 1.25 x initial limit			
		ESR	Within initial limits			
Storage Life	125°C @ 0 Volts, 2,000 hours	Δ C/C	Within ±10% of initial value			
		DF	Within initial limits			
		DCL	Within 1.25 x initial limit			
		ESR	Within initial limits			
Thermal Shock	MIL-STD-202, Method 107, Condition B, mounted, -55°C to 125°C, 1,000 cycles	Δ C/C	Within ±5% of initial value			
		DF	Within initial limits			
		DCL	Within 1.25 x initial limit			
		ESR	Within initial limits			
Temperature Stability	Extreme temperature exposure at a succession of continuous steps at +25°C, -55°C, +25°C, +85°C, +125°C, +25°C	+25°C	-55°C	+85°C	+125°C	
		Δ C/C	IL*	±10%	±10%	±20%
		DF	IL	IL	1.5 x IL	1.5 x IL
Surge Voltage	25°C and 85°C, 1.32 x rated voltage 1,000 cycles (125°C, 1.2 x rated voltage)	DCL	IL			
		ESR	n/a			
			10 x IL			
Mechanical Shock/Vibration	MIL-STD-202, Method 213, Condition I, 100 G Peak MIL-STD-202, Method 204, Condition D, 10 Hz to 2,000 Hz, 20 G peak	Δ C/C	Within ±10 of initial value			
		DF	Within initial limits			
		DCL	Within initial limits			
Additional Qualification Tests per MIL-PRF-55365/8	Please contact KEMET for more information.					

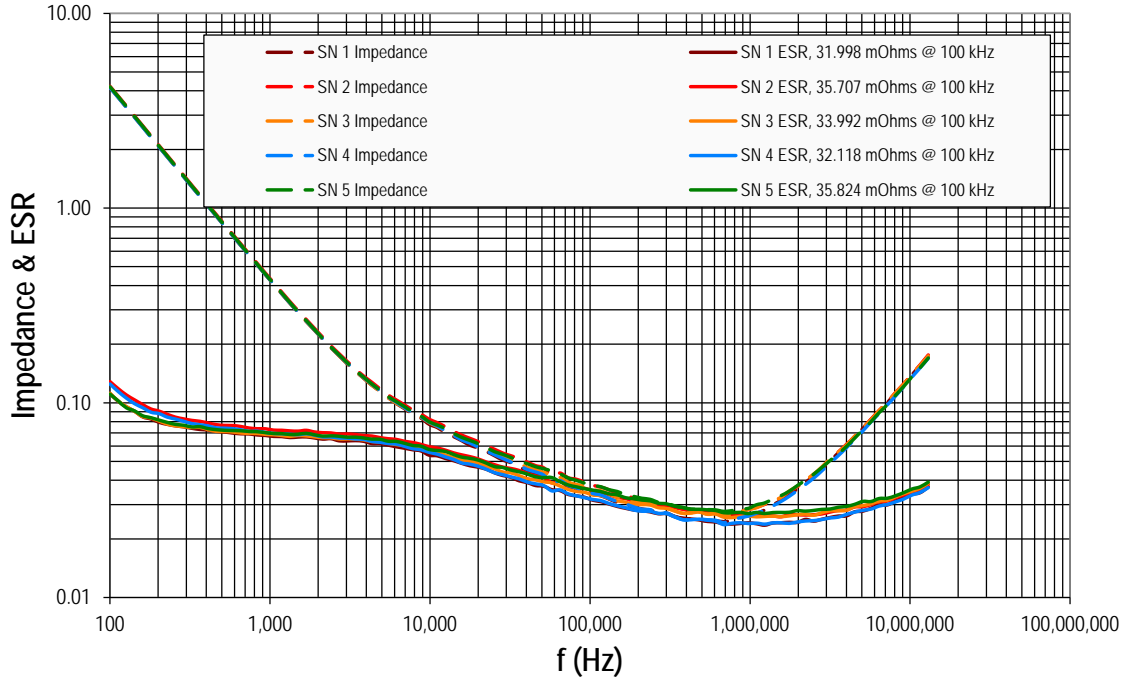
\*IL = Initial limit

## Certification

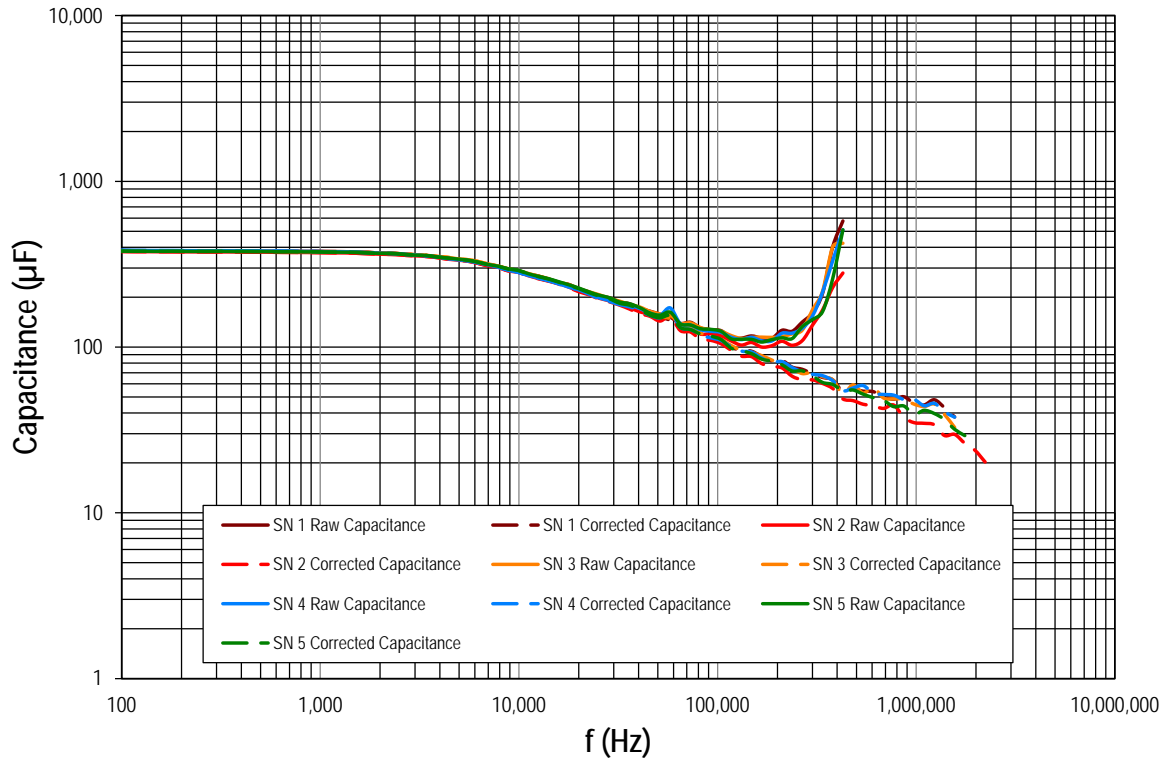
MIL-PRF-55365/8

## Electrical Characteristics

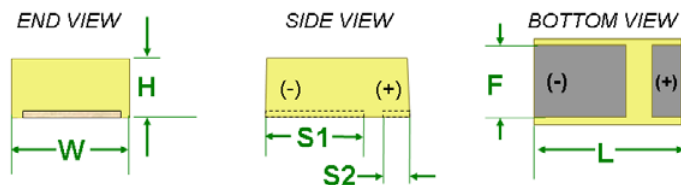
### Impedance & ESR vs. Frequency



### Capacitor vs. Frequency



## Dimensions – Millimeters



Case Size		Component					
KEMET	EIA	L	W	H	F ±0.2	S1 ±0.2	S2 ±0.2
P	7260-38	7.2	6.0 ±0.3	3.5 ±0.3	4.95	1.6	1.6

### Table 1 – Ratings & Part Number Reference

Rated Voltage	Rated Capacitance	Case Code/ Case Size	KEMET Part Number	DC Leakage	DF%	Standard ESR	Low ESR	Ultra-Low ESR
VDC	µF	KEMET/EIA	(See below for part options)	µA @ +20°C Max/5 Min	% @ +20°C 120 Hz Max	mΩ @ +20°C 100 kHz Max	mΩ @ +20°C 100 kHz Max	Ω @ +20°C 100 kHz Max
4	470	P/7260-38	T428P477(1)004(2)(3)(4)(5)	18.8	10.0	130	45	NA
6.3	390	P/7260-38	T428P397(1)006(2)(3)(4)(5)	24.6	8.0	130	45	NA
6.3	470	P/7260-38	T428P477(1)006(2)(3)(4)(5)	29.6	10.0	120	50	NA
10	330	P/7260-38	T428P337(1)010(2)(3)(4)(5)	33.0	8.0	130	45	NA
16	180	P/7260-38	T428P187(1)016(2)(3)(4)(5)	28.8	8.0	130	55	NA
16	220	P/7260-38	T428P227(1)016(2)(3)(4)(5)	35.2	8.0	120	55	NA
20	150	P/7260-38	T428P157(1)020(2)(3)(4)(5)	30.0	8.0	140	100	NA
25	68	P/7260-38	T428P686(1)025(2)(3)(4)(5)	17.0	6.0	200	95	NA
35	22	P/7260-38	T428P226(1)035(2)(3)(4)(5)	7.7	6.0	280	220	NA
50	15	P/7260-38	T428P156(1)050(2)(3)(4)(5)	7.5	6.0	400	350	NA
VDC	µF	KEMET/EIA	(See below for part options)	µA @ +20°C Max/5 Min	% @ +20°C 120 Hz Max	mΩ @ +20°C 100 kHz Max	mΩ @ +20°C 100 kHz Max	Ω @ +20°C 100 kHz Max
Rated Voltage (V)	Rated Cap (µF)	Case Code/ Case Size	KEMET Part Number	DC Leakage	DF	Standard ESR	Low ESR	Ultra-Low ESR

(1) To complete KEMET part number, insert J for ±5%, K for ±10% and M for ±20%. Designates capacitance tolerance.

(2) To complete KEMET part number, insert B (0.1%/1,000 hours) or A = N/A.

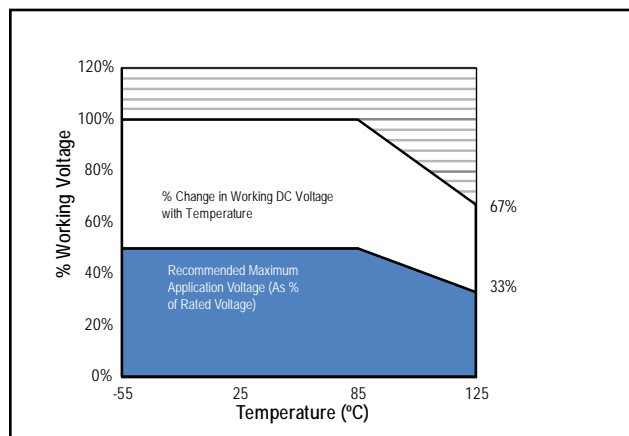
(3) To complete KEMET part number, insert H = solder plated or T = 100% tin (Sn). Designates termination finish.

(4) To complete KEMET part number, insert 61 = none, 62 = 10 cycles +25°C or 63 = 10 cycles -55°C +85°C. Designates surge current option.

(5) To complete KEMET part number, insert 10 = standard, 20 = low or 30 = ultra-low. Designates ESR option.

Please refer to Ordering Information for additional details.

## Recommended Voltage Derating Guidelines



## Ripple Current/Ripple Voltage

Case Code		Maximum Power Dissipation (P max) mWatts @ 25°C with +20°C Rise
KEMET	EIA	
A	3216-18	75
B	3528-21	85
C	6032-28	110
D	7343-31	150
X	7343-43	165
E	7260-38	200
T428P	7260-38	325
R	2012-12	25
S	3216-12	60
T	3528-12	70
U	6032-15	90
V	7343-20	125
T510X	7343-43	270
T510E	7260-38	285

Temperature Compensation Multipliers for Maximum Power Dissipation		
≤ 25°C	85°C	125°C
1.00	0.90	0.40

*T* = Environmental Temperature

Using the P max of the device, the maximum allowable rms ripple current or voltage may be determined.

$$I(max) = \sqrt{P_{max}/R}$$

$$E(max) = \sqrt{P_{max} \cdot R}$$

*I* = rms ripple current (amperes)

*E* = rms ripple voltage (volts)

*P max* = maximum power dissipation (watts)

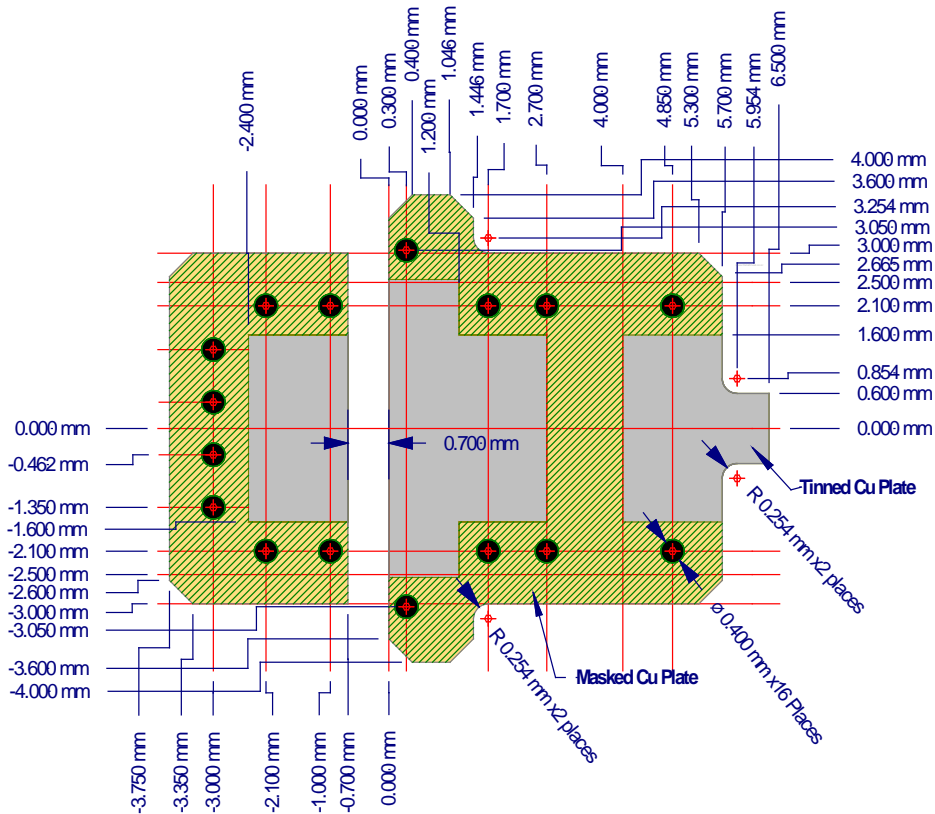
*R* = ESR at specified frequency (ohms)

## Reverse Voltage

Solid tantalum capacitors are polar devices and may be permanently damaged or destroyed if connected with the wrong polarity. The positive terminal is identified on the capacitor body by a stripe, plus in some cases a beveled edge. A small degree of transient reverse voltage is permissible for short periods per the below table. The capacitors should not be operated continuously in reverse mode, even within these limits.

Temperature	Permissible Transient Reverse Voltage
25°C	15% of Rated Voltage
85°C	5% of Rated Voltage
125°C	1% of Rated Voltage

**Table 2 – Land Dimensions/Courtyard**



## Soldering Process

KEMET's families of surface mount capacitors are compatible with wave (single or dual), convection, IR or vapor phase reflow techniques. Preheating of these components is recommended to avoid extreme thermal stress. KEMET's recommended profile conditions for convection and IR reflow reflect the profile conditions of the IPC/J-STD-020D standard for moisture sensitivity testing. The devices can safely withstand a maximum of three reflow passes at these conditions.

Note that although the X/7343-43 case size can withstand wave soldering, the tall profile (4.3 mm maximum) dictates care in wave process development.

Hand soldering should be performed with care due to the difficulty in process control. If performed, care should be taken to avoid contact of the soldering iron to the molded case. The iron should be used to heat the solder pad, applying solder between the pad and the termination, until reflow occurs. Once reflow occurs, the iron should be removed immediately. "Wiping" the edges of a chip and heating the top surface is not recommended.

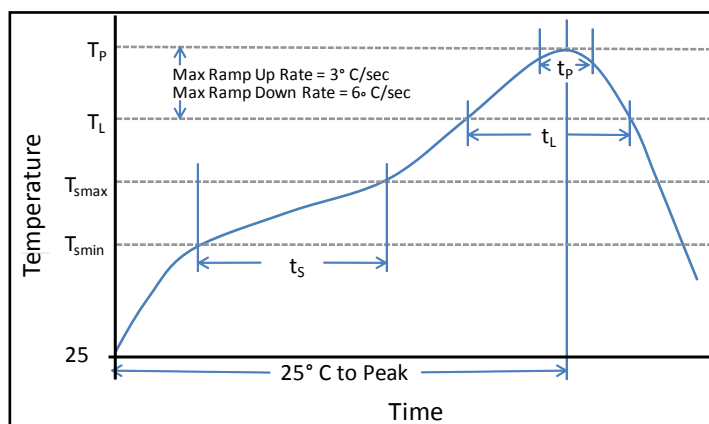
During typical reflow operations, a slight darkening of the gold-colored epoxy may be observed. This slight darkening is normal and is not harmful to the product. Marking permanency is not affected by this change.

Profile Feature	SnPb Assembly	Pb-Free Assembly
<b>Preheat/Soak</b>		
Temperature Minimum ( $T_{Smin}$ )	100°C	150°C
Temperature Maximum ( $T_{Smax}$ )	150°C	200°C
Time ( $t_s$ ) from $T_{Smin}$ to $T_{Smax}$	60-120 seconds	60-120 seconds
Ramp-up Rate ( $T_L$ to $T_P$ )	3°C/seconds maximum	3°C/seconds maximum
Liquidous Temperature ( $T_L$ )	183°C	217°C
Time Above Liquidous ( $t_L$ )	60-150 seconds	60-150 seconds
Peak Temperature ( $T_P$ )	220°C* 235°C**	250°C* 260°C**
Time within 5°C of Maximum Peak Temperature ( $t_p$ )	20 seconds maximum	30 seconds maximum
Ramp-down Rate ( $T_P$ to $T_L$ )	6°C/seconds maximum	6°C/seconds maximum
Time 25°C to Peak Temperature	6 minutes maximum	8 minutes maximum

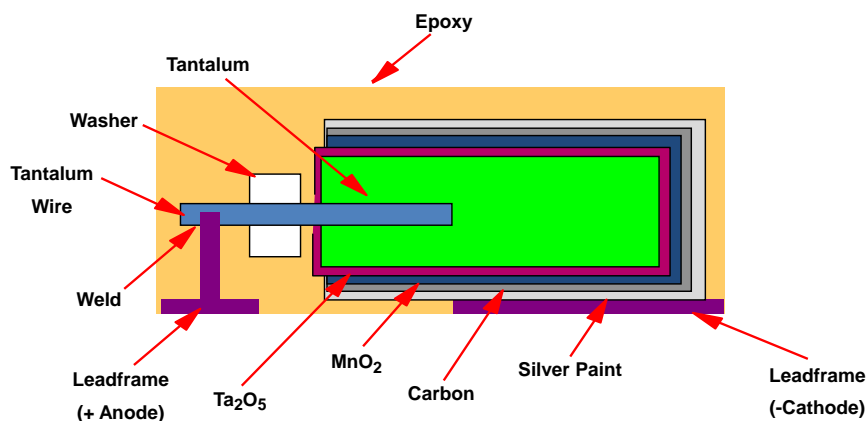
Note: All temperatures refer to the center of the package, measured on the package body surface that is facing up during assembly reflow.

\*Case Size D, E, P, Y and X

\*\*Case Size A, B, C, H, I, K, M, R, S, T, U, V, W and Z

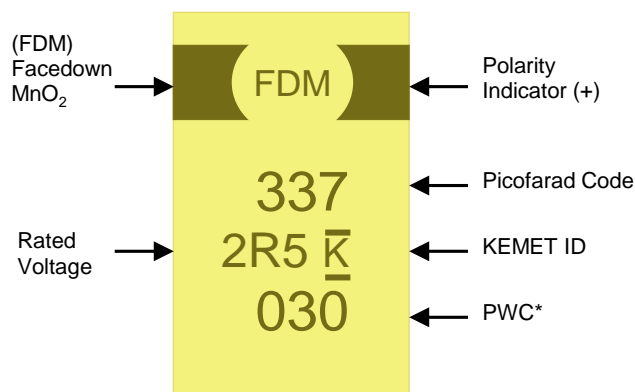


## Construction





## Capacitor Marking



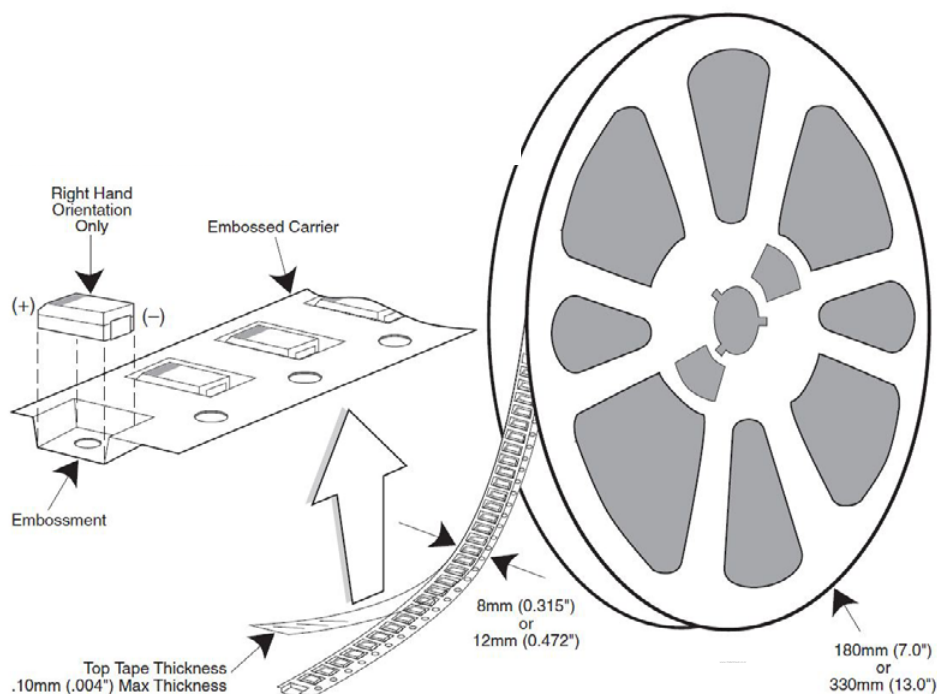
\* 010 = 30<sup>th</sup> week of 2010

## Storage

Tantalum chip capacitors should be stored in normal working environments. While the chips themselves are quite robust in other environments, solderability will be degraded by exposure to high temperatures, high humidity, corrosive atmospheres, and long term storage. In addition, packaging materials will be degraded by high temperature-reels may soften or warp, and tape peel force may increase. KEMET recommends that maximum storage temperature not exceed 40°C, and maximum storage humidity not exceed 60% relative humidity. Temperature fluctuations should be minimized to avoid condensation on the parts, and atmospheres should be free of chlorine and sulphur bearing compounds. For optimized solderability, chip stock should be used promptly, preferably within three years of receipt.

## Tape & Reel Packaging Information

KEMET's molded tantalum and aluminum chip capacitor families are packaged in 8 and 12 mm plastic tape on 7" and 13" reels in accordance with *EIA Standard 481-1: Embossed carrier taping of Surface Mount Components for Automatic Handling*. This packaging system is compatible with all tape fed automatic pick-and-place systems.

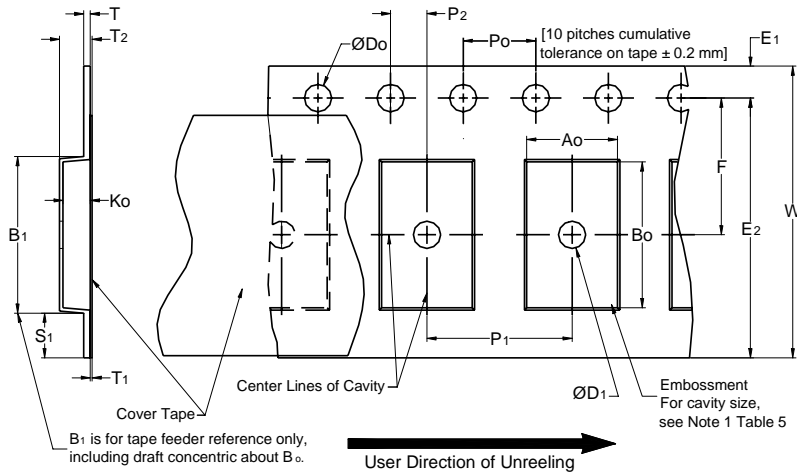


**Table 3 – Packaging Quantity**

Case Code		Tape Width (mm)	7" Reel*	13" Reel*
KEMET	EIA			
R	2012-12	8	2,500	10,000
I	3216-10	8	3,000	12,000
S	3216-12	8	2,500	10,000
T	3528-12	8	2,500	10,000
M	3528-15	8	2,000	8,000
U	6032-15	12	1,000	5,000
L	6032-19	12	1,000	5,000
W	7343-15	12	1,000	3,000
Z	7343-17	12	1,000	3,000
V	7343-20	12	1,000	3,000
A	3216-18	8	2,000	9,000
B	3528-21	8	2,000	8,000
C	6032-28	12	500	3,000
D	7343-31	12	500	2,500
Y	7343-40	12	500	2,000
X	7343-43	12	500	2,000
E/T428P	7260-38	12	500	2,000

\* No C-Spec required for 7" reel packaging. C-7280 required for 13" reel packaging.

**Figure 1 – Embossed (Plastic) Carrier Tape Dimensions**



**Table 4 – Embossed (Plastic) Carrier Tape Dimensions**

Metric will govern

Constant Dimensions — Millimeters (Inches)									
Tape Size	D <sub>0</sub>	D <sub>1</sub> Minimum Note 1	E <sub>1</sub>	P <sub>0</sub>	P <sub>2</sub>	R Ref. Note 2	S <sub>1</sub> Minimum Note 3	T Maximum	T <sub>1</sub> Maximum
8 mm	1.5 +0.10/-0.0 (0.059 +0.004/-0.0)	1.0 (0.039)	1.75 ±0.10 (0.069 ±0.004)	4.0 ±0.10 (0.157 ±0.004)	2.0 ±0.05 (0.079 ±0.002)	25.0 (0.984)	0.600 (0.024)	0.600 (0.024)	0.100 (0.004)
12 mm		1.5 (0.059)				30 (1.181)			
16 mm									
Variable Dimensions — Millimeters (Inches)									
Tape Size	Pitch	B <sub>1</sub> Maximum Note 4	E <sub>2</sub> Minimum	F	P <sub>1</sub>	T <sub>2</sub> Maximum	W Maximum	A <sub>0</sub> , B <sub>0</sub> & K <sub>0</sub>	
8 mm	Single (4 mm)	4.35 (0.171)	6.25 (0.246)	3.5 ±0.05 (0.138 ±0.002)	4.0 ±0.10 (0.157 ±0.004)	2.5 (0.098)	8.3 (0.327)	Note 5	
12 mm	Single (4 mm) & Double (8 mm)	8.2 (0.323)	10.25 (0.404)	5.5 ±0.05 (0.217 ±0.002)	8.0 ±0.10 (0.315 ±0.004)	4.6 (0.181)	12.3 (0.484)		
16 mm	Triple (12 mm)	12.1 (0.476)	14.25 (0.561)	5.5 ±0.05 (0.217 ±0.002)	8.0 ±0.10 (0.315 ±0.004)	4.6 (0.181)	16.3 (0.642)		

- The embossment hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of embossment location and hole location shall be applied independent of each other.
  - The tape with or without components shall pass around R without damage (see Figure 5).
  - If S<sub>1</sub> < 1.0 mm, there may not be enough area for cover tape to be properly applied (see EIA Standard 481–D, paragraph 4.3, section b).
  - B<sub>1</sub> dimension is a reference dimension for tape feeder clearance only.
  - The cavity defined by A<sub>0</sub>, B<sub>0</sub> and K<sub>0</sub> shall surround the component with sufficient clearance that:
    - the component does not protrude above the top surface of the carrier tape.
    - the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.
    - rotation of the component is limited to 20° maximum for 8 and 12 mm tapes and 10° maximum for 16 mm tapes (see Figure 3).
    - lateral movement of the component is restricted to 0.5 mm maximum for 8 mm and 12 mm wide tape and to 1.0 mm maximum for 16 mm tape (see Figure 4).
- See Addendum in EIA Standard 481–D for standards relating to more precise taping requirements.

## Packaging Information Performance Notes

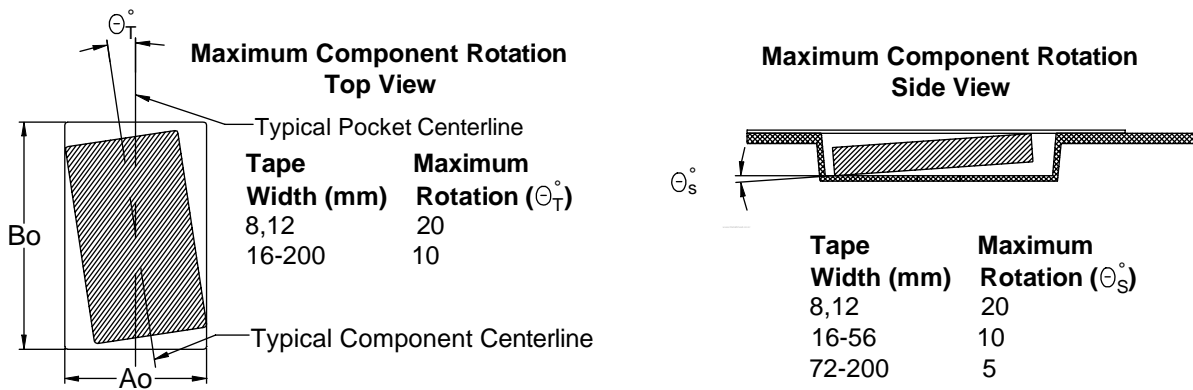
- 1. Cover Tape Break Force:** 1.0 Kg minimum.
- 2. Cover Tape Peel Strength:** The total peel strength of the cover tape from the carrier tape shall be:

Tape Width	Peel Strength
8 mm	0.1 to 1.0 Newton (10 to 100 gf)
12 and 16 mm	0.1 to 1.3 Newton (10 to 130 gf)

The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall be 165° to 180° from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity of 300 ±10 mm/minute.

- 3. Labeling:** Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket holes. Refer to EIA Standards 556 and 624.

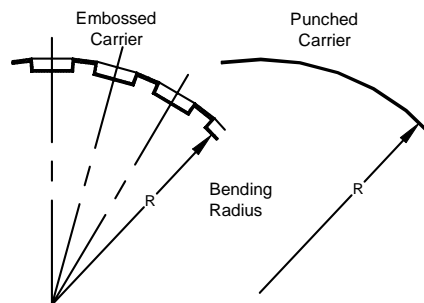
### Figure 2 – Maximum Component Rotation



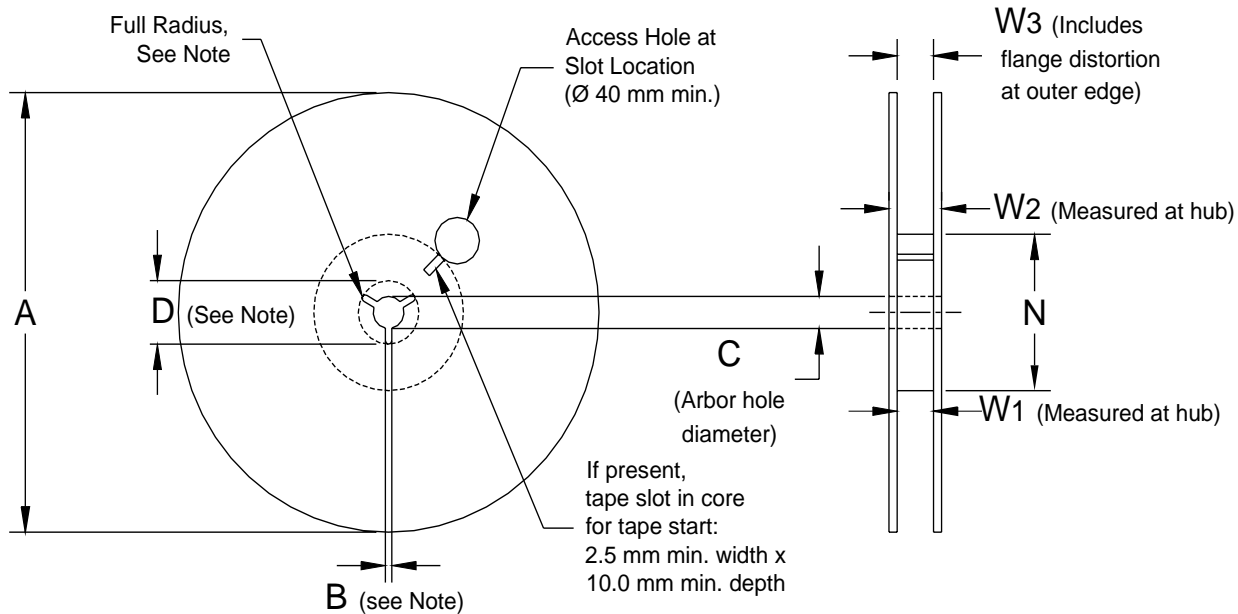
### Figure 3 – Maximum Lateral Movement



### Figure 4 – Bending Radius



**Figure 5 – Reel Dimensions**



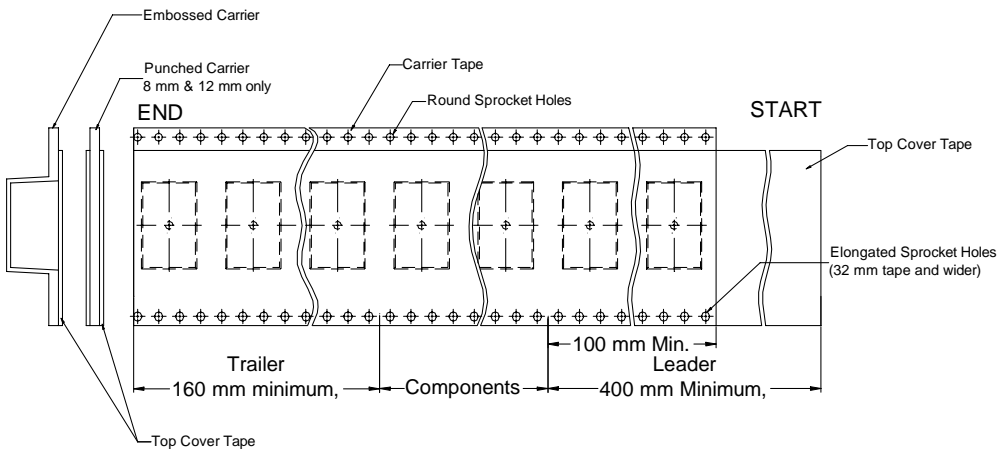
Note: Drive spokes optional; if used, dimensions B and D shall apply.

**Table 5 – Reel Dimensions**

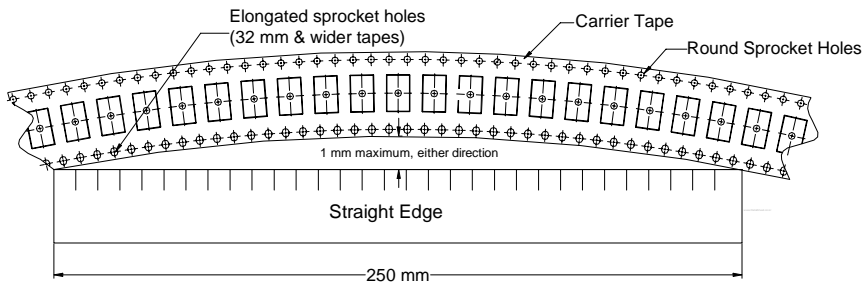
Metric will govern

Constant Dimensions — Millimeters (Inches)				
Tape Size	A	B Minimum	C	D Minimum
8 mm	178 ±0.20 (7.008 ±0.008)	1.5 (0.059)	13.0 +0.5/-0.2 (0.521 +0.02/-0.008)	20.2 (0.795)
12 mm	or			
16 mm	330 ±0.20 (13.000 ±0.008)			
Variable Dimensions — Millimeters (Inches)				
Tape Size	N Minimum	W <sub>1</sub>	W <sub>2</sub> Maximum	W <sub>3</sub>
8 mm	50 (1.969)	8.4 +1.5/-0.0 (0.331 +0.059/-0.0)	14.4 (0.567)	Shall accommodate tape width without interference
12 mm		12.4 +2.0/-0.0 (0.488 +0.078/-0.0)	18.4 (0.724)	
16 mm		16.4 +2.0/-0.0 (0.646 +0.078/-0.0)	22.4 (0.882)	

**Figure 6 – Tape Leader & Trailer Dimensions**



**Figure 7 – Maximum Camber**



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Tel: 33-1-4646-1009

Sasso Marconi, Italy  
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Milan, Italy  
Tel: 39-02-57518176

Rome, Italy  
Tel: 39-06-23231718

Madrid, Spain  
Tel: 34-91-804-4303

### Central Europe

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Tel: 49-8191-3350800

Dortmund, Germany  
Tel: 49-2307-3619672

Kwidzyn, Poland  
Tel: 48-55-279-7025

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Bishop's Stortford, United Kingdom  
Tel: 44-1279-757201

Weymouth, United Kingdom  
Tel: 44-1305-830747

Coatbridge, Scotland  
Tel: 44-1236-434455

Färjestaden, Sweden  
Tel: 46-485-563934

Espoo, Finland  
Tel: 358-9-5406-5000

## Asia

### Northeast Asia

Hong Kong  
Tel: 852-2305-1168

Shenzhen, China  
Tel: 86-755-2518-1306

Beijing, China  
Tel: 86-10-5829-1711

Shanghai, China  
Tel: 86-21-6447-0707

Taipei, Taiwan  
Tel: 886-2-27528585

### Southeast Asia

Singapore  
Tel: 65-6586-1900

Penang, Malaysia  
Tel: 60-4-6430200

Bangalore, India  
Tel: 91-806-53-76817

*Note: KEMET reserves the right to modify minor details of internal and external construction at any time in the interest of product improvement. KEMET does not assume any responsibility for infringement that might result from the use of KEMET Capacitors in potential circuit designs. KEMET is a registered trademark of KEMET Electronics Corporation.*

## Other KEMET Resources

Tools	
Resource	Location
Configure A Part: CapEdge	<a href="http://capacitoredge.kemet.com">http://capacitoredge.kemet.com</a>
SPICE & FIT Software	<a href="http://www.kemet.com/spice">http://www.kemet.com/spice</a>
Search Our FAQs: KnowledgeEdge	<a href="http://www.kemet.com/keask">http://www.kemet.com/keask</a>

Product Information	
Resource	Location
Products	<a href="http://www.kemet.com/products">http://www.kemet.com/products</a>
Technical Resources (Including Soldering Techniques)	<a href="http://www.kemet.com/technicalpapers">http://www.kemet.com/technicalpapers</a>
RoHS Statement	<a href="http://www.kemet.com/rohs">http://www.kemet.com/rohs</a>
Quality Documents	<a href="http://www.kemet.com/qualitydocuments">http://www.kemet.com/qualitydocuments</a>

Product Request	
Resource	Location
Sample Request	<a href="http://www.kemet.com/sample">http://www.kemet.com/sample</a>
Engineering Kit Request	<a href="http://www.kemet.com/kits">http://www.kemet.com/kits</a>

Contact	
Resource	Location
Website	<a href="http://www.kemet.com">www.kemet.com</a>
Contact Us	<a href="http://www.kemet.com/contact">http://www.kemet.com/contact</a>
Investor Relations	<a href="http://www.kemet.com/ir">http://www.kemet.com/ir</a>
Call Us	1-877-MyKEMET
Twitter	<a href="http://twitter.com/kemetcapacitors">http://twitter.com/kemetcapacitors</a>

## Disclaimer

All product specifications, statements, information and data (collectively, the "Information") are subject to change without notice.

All Information given herein is believed to be accurate and reliable, but is presented without guarantee, warranty, or responsibility of any kind, expressed or implied.

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Although we design and manufacture our products to the most stringent quality and safety standards, given the current state of the art, isolated component failures may still occur. Accordingly, customer applications which require a high degree of reliability or safety should employ suitable designs or other safeguards (such as installation of protective circuitry or redundancies) in order to ensure that the failure of an electrical component does not result in a risk of personal injury or property damage.

Although all product-related warnings, cautions and notes must be observed, the customer should not assume that all safety measures are indicated or that other measures may not be required.



